

FEATURES

- | 200W Peak Pulse Power ($t_p=8/20\mu s$)
- | Protects tow I/O lines
- | Working voltages : 24 V
- | Low leakage current
- | Low clamping voltage
- | Response time is < 1 ns

APPLICATIONS

- | High-Speed Data Transmission Interfaces
- | Cellular Phones
- | Portable Electronics
- | Wireless Bus Protection



SOT-323



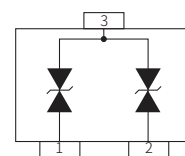
Marking

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003



Schematic Symbol

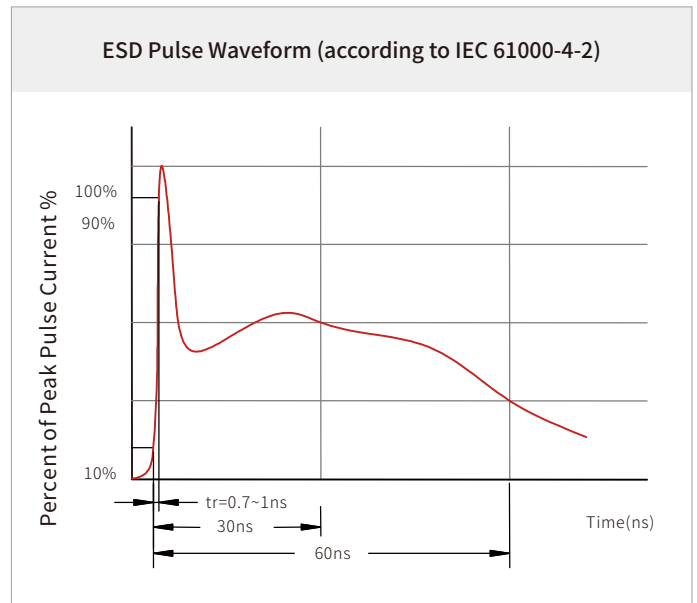
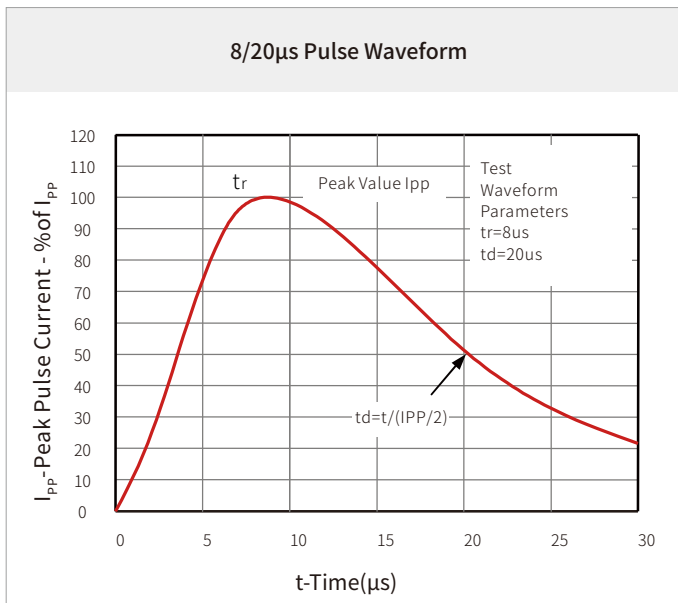
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P_{pp}	Peak Pulse Power ($t_p=8/20\mu s$ waveform)	200	Watts
T_J	Operating Temperature Range	-55 to +150	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

ELECTRICAL CHARACTERISTICS

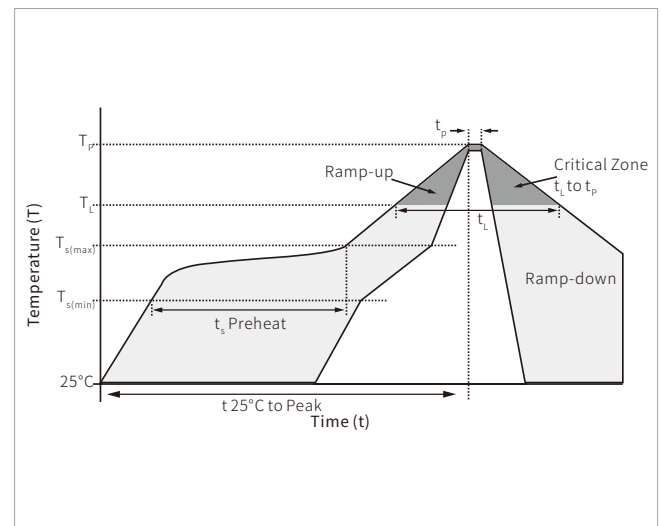
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V_{RWM}	Reverse Stand-off Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	$I_T=1mA$	26.7			V
I_R	Reverse Leakage Current	$V_{RWM}=24V$			1	μA
V_C	Clamping Voltage	$I_{pp}=1A, t_p=8/20\mu s$			43	V
V_C	Clamping Voltage	$I_{pp}=4A, t_p=8/20\mu s$			50	V
I_{PP}	Peak Pulse Current	$t_p=8/20\mu s$			4	A
C_J	Off State Junction Capacitance	$V_R=0V, f=1MHz$		12	18	pF

CHARACTERISTIC CURVES

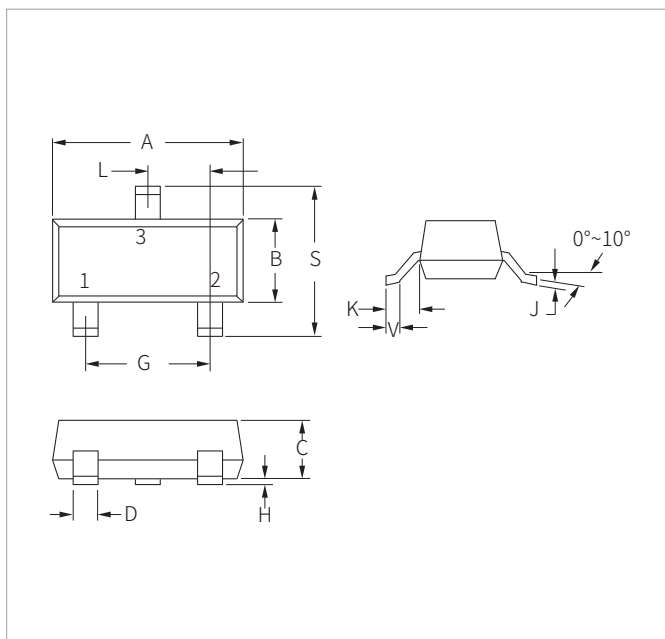


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

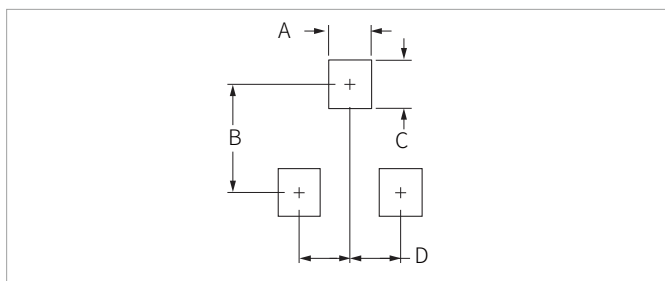


SOT-323 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.00	2.20	0.079	0.087
B	1.15	1.35	0.045	0.053
C	0.80	1.10	0.031	0.043
D	0.20	0.40	0.008	0.016
G	1.20	1.40	0.047	0.055
H	0.00	0.10	0.000	0.004
J	0.08	0.15	0.003	0.006
K	0.525REF		0.021REF	
L	0.650TYP		0.026TYP	
S	2.15	2.45	0.085	0.096
V	0.26	0.46	0.010	0.018

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters	Inches
	NOR	NOR
A	0.50	0.020
B	2.20	0.087
C	0.80	0.031
D	1.30	0.051

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SE33T20B24B	SOT-323	3000PCS	7"

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